IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) An apparatus for dissipating heat from an electronic device, the apparatus comprising:

a housing adapted to be closely fitted to a heat sink; the housing having a first end and a second end each configured to receive an interchangeable cooling attachment; and

an air moving device adapted to be interchangeably coupled to [[a]] the first end of the housing, the air moving device to move air through the housing.

2. (Previously Presented) The apparatus of claim 1 further comprising an air duct coupled to the second end of the housing, the air duct to direct the flow of air from an exterior of a chassis to the housing.

3. (Original) The apparatus of claim 2 wherein the air duct is a flexible hose.

4. (Original) The apparatus of claim 3 wherein the air duct is an extendable hose.

5. (Original) The apparatus of claim 2 wherein the air duct is rigid.

6. (Original) The apparatus of claim 1 wherein the air moving device is a fan.

7. (Original) The apparatus of claim 6 wherein the fan has a diameter of between about 20 millimeters and about 120 millimeters.

8. (Original) The apparatus of claim 6 wherein the fan has a diameter of about 60 millimeters.

9. (Original) The apparatus of claim 6 wherein the fan is coupled to the housing at a distance from the heat sink that is about equal to a diameter of the fan.

10. (Original) The apparatus of claim 6 wherein the fan is coupled to the housing at a distance from the heat sink that is less than a diameter of the fan.

11. – 14. (Cancelled)

15. (Currently Amended) A computerized system comprising:

a chassis;

an integrated circuit board mounted in the chassis;

a processor coupled to the integrated circuit board; and

a processor cooling system coupled to the processor, the processor cooling system comprising:

a heat sink coupled to the processor;

a housing coupled to the heat sink, the housing positioned in close proximity to the heat sink; and

a fan interchangeably coupled to the housing, the fan to create a flow of air through the housing and the fan positioned at a distance from the housing that is about equal to or less than a diameter of the fan.

16. (Original) The computerized system of claim 15 further comprising a first air duct coupled to the housing and to the chassis, the air duct to channel external ambient air to the heat sink.

17. (Original) The computerized system of claim of claim 16 further comprising a second air duct coupled to the housing and to the chassis, the second air duct to channel heated air away from the heat sink and out of the chassis.

18. (Currently Amended) ~~The computerized system of claim 15 further comprising:~~

A computerized system comprising:

a chassis;

an integrated circuit board mounted in the chassis;

a processor coupled to the integrated circuit board; and

a processor cooling system coupled to the processor, the processor cooling system comprising:

a heat sink coupled to the processor;

a housing coupled to the heat sink, the housing positioned in close proximity to the heat sink;

a fan interchangeably coupled to the housing, the fan to create a flow of air through the housing;

a second fan coupled to the housing; and

an air duct coupled to the housing.

19. (Currently Amended) ~~The computerized system of claim 15 further comprising:~~

A computerized system comprising:

a chassis;

an integrated circuit board mounted in the chassis;

a processor coupled to the integrated circuit board; and

a processor cooling system coupled to the processor, the processor cooling system comprising:

a heat sink coupled to the processor;

a housing coupled to the heat sink, the housing positioned in close proximity to the heat sink;

a fan interchangeably coupled to the housing, the fan to create a flow of air through the housing;

a second processor coupled to the integrated circuit board;

a second heat sink coupled to the second processor;

a second housing coupled to the second heat sink, the second housing positioned in close proximity to the second heat sink;

a second fan coupled to the second housing; and

a housing connector coupled to the first housing and the second housing.

20. (Currently Amended) A method of assembling a cooling system for an integrated circuit, the method comprising:

closely coupling a housing to a heat sink for an integrated circuit; and

interchangeably coupling a fan to the housing at a distance that is about equal to or less than a diameter of the fan.

21. (Original) The method of claim 20 further comprising coupling one or more cooling attachments to the housing.

22. (Original) The method of claim 21 wherein coupling one or more cooling attachments to the housing comprises coupling an air duct to the housing and to a chassis.

23. (Previously Presented) The method of claim 22 further comprising coupling a cooling attachment to the fan.

24. (Original) The method of claim 23 wherein coupling a cooling attachment to the fan further comprises coupling an extendable, flexible hose to the fan and to the chassis.

25. – 27. (Cancelled)

28. (Original) A kit of parts for an electronic component cooling system, the kit comprising:

one or more heat sink housings adapted to fit over a heat sink for an electronic component; and

a plurality of interchangeable cooling attachments adapted to be combined with the one or more heat sink housings to form an electronic component cooling system.

29. (Original) The kit of parts as claimed in claim 28 further comprising a fan adapted to be coupled to the one or more heat sink housings.

30. (Original) The kit of parts as claimed in claim 28 wherein the plurality of cooling attachments are selected from the group consisting of: a housing air duct adapter, an air inlet chassis adapter, a housing fan adapter, a housing connector, a chassis fan adapter, and a splitter.